

# Technic MP200

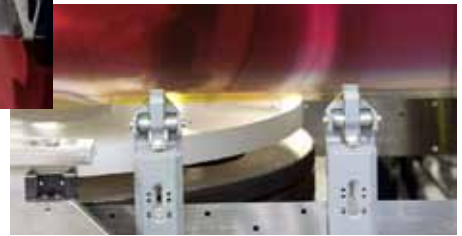
Advanced Vertical Plating for Thin Substrates



## Technic MP200

The Technic MP200 is an advanced VCP design for plating of thin substrates in panel, cut sheet or roll. The equipment can be adapted to seed layer plating as well as panel or pattern plating of copper, tin, nickel and or gold. The Technic MP200 perfects the VCP concept and provides:

- Effective handling of thin substrates
- World class distribution and throwing power
- Low maintenance time and cost
- A perfect plated surface
- Reduced water usage



## Excellent Material Handling of Thin Substrates

The Technic MP200 can transport material as thin as 12 microns and from 200 to 600 mm width. The system utilizes a top & optional bottom conveyor where the material is clipped and held under controlled tension. This eliminates the need for contact rollers, a major cause of defects. Top and bottom conveyors are synchronized through servo controlled drives. Material can be transported in rolls or in sheet form from stacks.

- Substrate thickness from 12 micron
- Closed loop tension control with servo drive and taper tension control
- Stable clip mounting platform promotes dimensional stability
- Edge detection and steering system for accurate control of roll build up
- Splice station and accumulator for semi-auto roll change
- Programmable length counter with roll change alarm
- Available tilt-down spindle or air bearing for horizontal loading
- Available multiple spindles and slitting

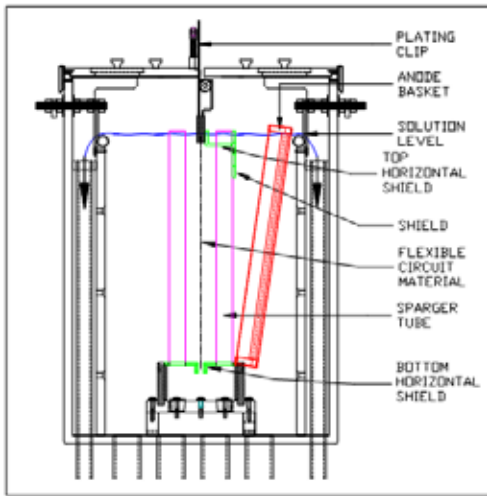


Tilt down/up spindle

## Superior Distribution with Excellent Throwing Power

The Technic MP200 improves the VCP concept through use of 3-dimensional shielding, specially designed solution flow, and proprietary soluble and insoluble anode systems. The end result is a surface distribution of + 5% and throwing power of over 90% in blind and through vias at 2-3X current densities in typical vertical process tanks.

- Adjustable 3-dimensional shield components provide excellent distribution control
- Anodes can be tilted to increase copper thickness at the bottom of the web
- Contact designed for consistent reduced insertion depth
- Choice of titanium basket with soluble anodes or IrO insoluble anode
- Technic ISA Membrane reduces oxidation of organic additive when using insoluble anodes

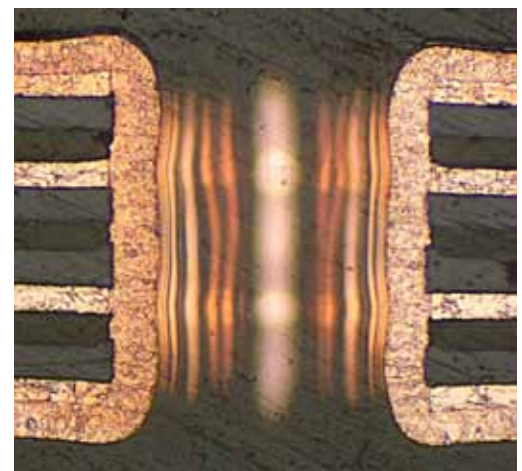
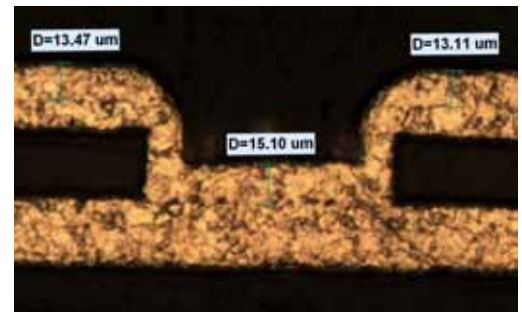
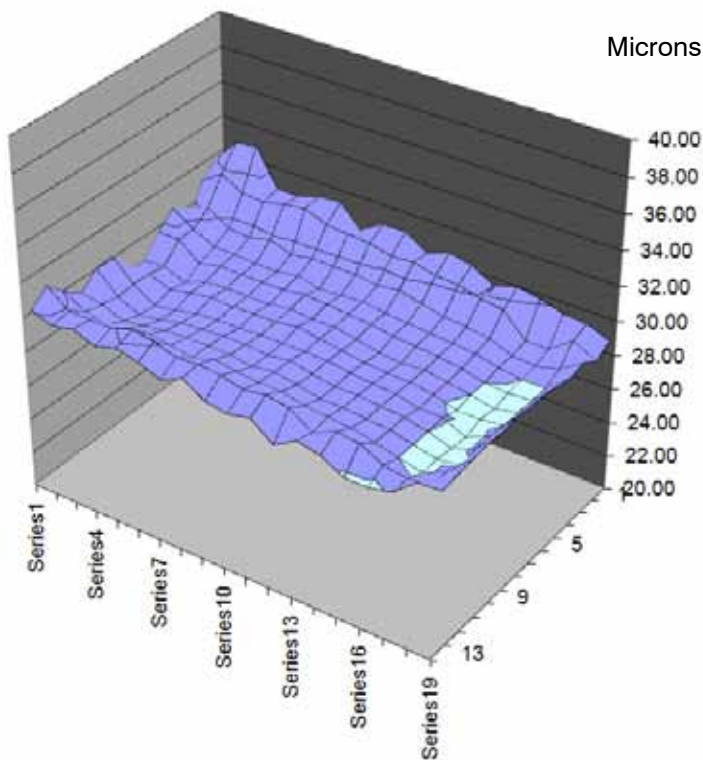


Easy load and position anode baskets



Filter Screen

## Plating Distribution



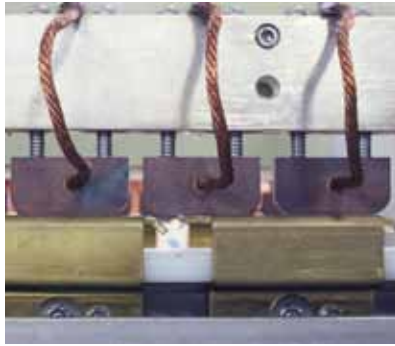
## Reduced Cost of Operation and Maintenance

The Technic MP200 has been engineered to reduce maintenance requirements, especially when compared to horizontal plating equipment. From minimal exposed contact area and replaceable contacts to isolated cathode contact and continuous tip stripping, the Technic MP200 provides consistency to maintain production quality and volumes.

- Interchangeable titanium contact with halar coating and welded tip
- Clip body and moving cathode connection isolated away from plating cell
- Clip strip on every cycle



Clip detail



Moving cathode contacts



Easy access utilities and service area

## A Perfect Copper Surface

The Technic MP200 can provide the defect free surface being demanded by the next generation of electronic devices. With soluble anodes, the solution is triple filtered prior to returning to the plating cell. If used in conjunction with the Technic ISA insoluble anode system, the major cause of debris, phosphorized anodes are eliminated without impacting additive consumption. The Technic MP200 makes processing advanced PCB designs practical today.

- Triple Filtration for Clean Operation
- Bottom sump and baffled returns insure complete turnover of solution during filtration
- Technic ISA eliminates particulates from phosphorized copper anodes
- Automatic replenishment system for copper oxide
- Homogeneous plating with no layer separation



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